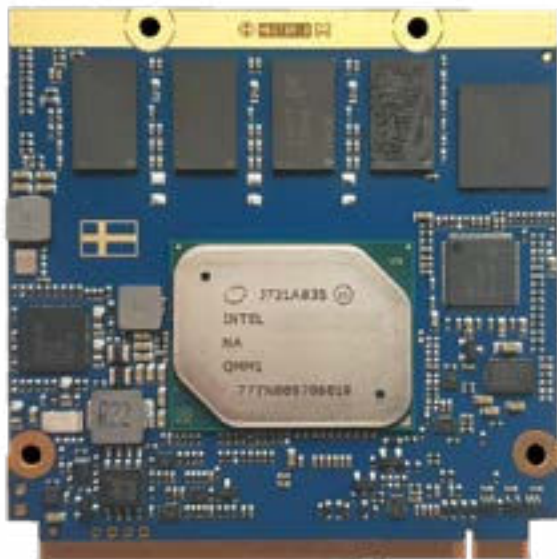# H6075
Qseven module with Intel® Atom™ SOC

The H6075 is a compact (70mm x 70mm) high-performance, low power COM module based on the Intel® Atom™ Apollo Lake System-on-Chip, SOC. The SOCs have the 9th generation Intel® HD Graphics Engine GPU built in along with a dual or quad core CPU and I/O controller.

The Qseven form factor makes H6075 a legacy free module with a full range of contemporary low voltage differential serial interfaces such as PCI Express, USB 3.0, SATA 3.0 and display interfaces such as DisplayPort or HDMI and Dual 24-bit LVDS.
Qseven modules are defined for low cost and ruggedness, with an MXM type edgecard connector interfacing the carrier board. H6075 has soldered memory and optional on-board eMMC Flash.
The H6075 is available in both standard and industrial grade operating temperature.

FEATURES

- Dual or Quad core Intel® Atom™ SOC
- 9th generation Intel® HD Graphics Engine
- Industrial temperature range (-40°C to +85°C)
- Up to three USB 3.0 or up to eight USB 2.0

- Optional on-board eMMC Flash storage (MLC/pSLC)
- Soldered DDR3L RAM memory
- Dual 24-bit LVDS and DisplayPort or DVI or HDMI
- Compatible with Q7 revision 2.1

LOOKING FOR SOMETHING SLIGHTLY DIFFRENT?

In most cases standard products can be customized to specification. With small modifications to hardware and software, you can have the qualitys and functions you need.

Call us. We will be happy to suggest and impliment changes in standard producys to meet your requirements exactly.

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H6075 - Technical Specifications

SOC (CPU+GPU+I/O)

AMD G-SeriesAPU, single or dual core with built-in GPU.
Intel® Atom™ x7-E3950
(Quad Core, 2.0/1.6 GHz, 12W TDP, -40°C to +85°C)

Intel® Atom™ x5-E3940
(Quad Core, 1.8/1.6 GHz, 9.5W TDP, -40°C to +85°C)

Intel® Atom™ x5-E3930
(Dual Core, 1.8/1.3 GHz, 6.5W TDP, -40°C to +85°C)

Intel® Pentium® N4200
(Quad Core, 2.5/1.1 GHz, 6W TDP)

Intel® Celeron® N3350
(Dual Core, 2.4/1.1 GHz, 6W TDP)

INTEGRATED GRAPHICS

Integrated 2D/3D/MPEG hardware acceleration

GPU: 9th generation Intel® HD Graphics Engine

MEMORY

Soldered DDR3L RAM with 2GB, 4GB or 8GB

ONBOARD Flash Storage (optional)

eMMC, up to 64 GB, configurable as MLC or pSLC

SATA

2 x SATA 3.0 ports

BATTERY MANAGEMENT

Support for Smart battery implementation on carrier board

POWER MANAGEMENT

ACPI 5.0 compliant Support for S3 and S4

SERIAL PORT

1 x COM (Tx, Rx, RTS, CTS)

BIOS Support for Super I/O on Carrier Board

SD Card

1 x SD Card port

USB

One of the following configurations:

a) 1 x USB 3.0 and 8 x USB 2.0

b) 2 x USB 3.0 and 6 x USB 2.0

c) 3 x USB 3.0 and 4 x USB 2.0

PCIE PORTS

4 x PCIe x1 Gen 2.0

LPC BUS

1 x LPC

ETHERNET

Intel® i210/i211 Gigabit Ethernet controller

SERIAL INTERFACE

I2C/SM Bus interface

BIOS

AMI Aptio V UEFI Bios

DISPLAY INTERFACE

Dual 24-bit LVDS and DisplayPort or DVI or HDMI

AUDIO

Support for HDA audio codec on carrier board

POWER

+5V +/-5%

OPERATING TEMPERATURE

Standard: 0°C to +60°C

Industrial: -40°C to +85°C

HUMIDITY

10 to 90% (operating)

5 to 95% (storage)

FORM FACTOR

Qseven Specification 2.1, 70mm x 70mm

OPTIONAL ACESSORIES

Q7 Evaluation Carrier Board

Heatspreader

Heatsink

Coating Service

BIOS Customization Service

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